

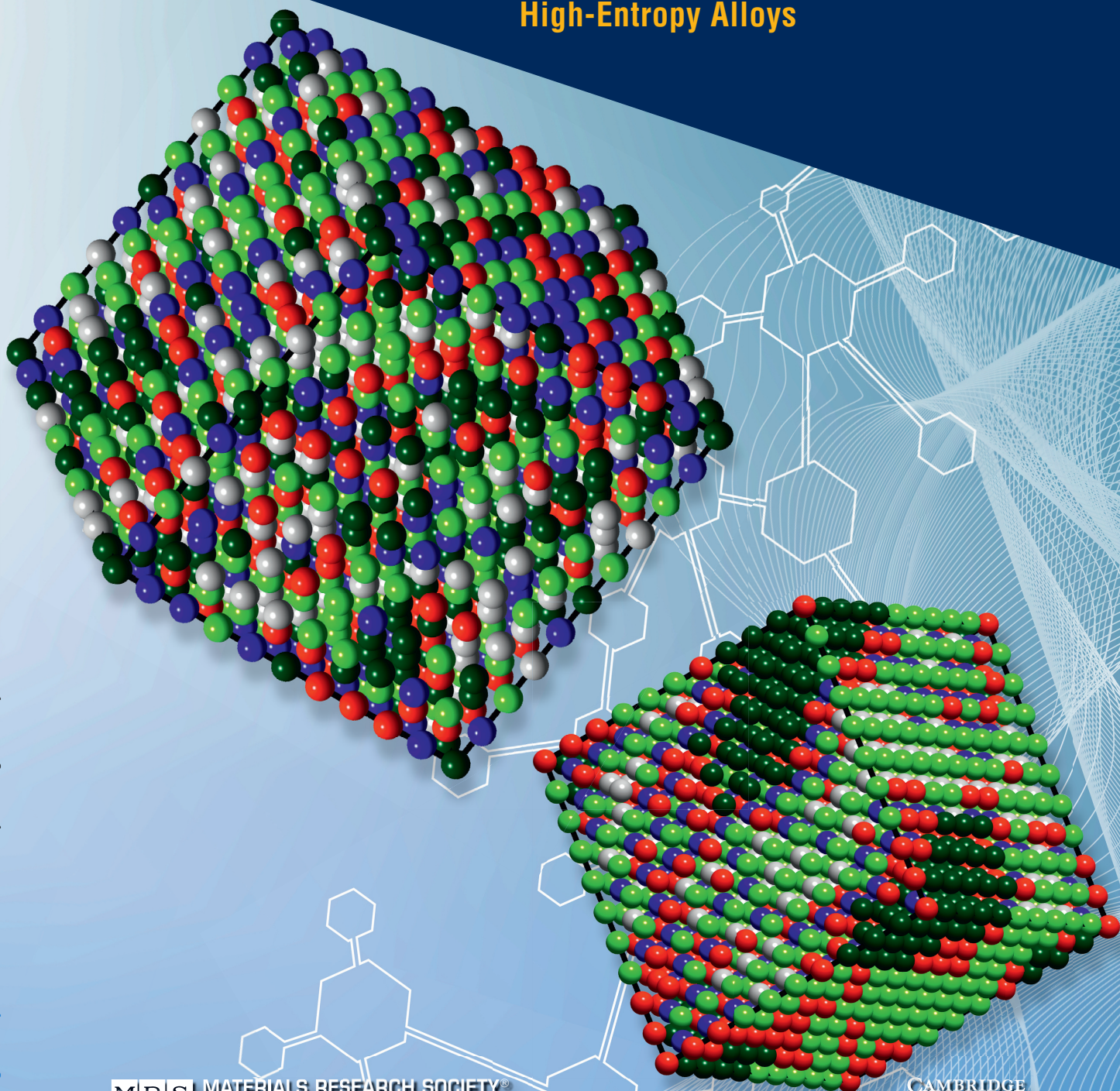


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Fundamental Understanding
and Applications of
High-Entropy Alloys



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